



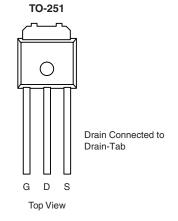
P-Channel 60-V (D-S), 175 °C MOSFET, Logic Level

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
- 60	0.170 at V _{GS} = - 10 V	- 10		
	0.280 at V _{GS} = - 4.5 V	- 8		

FEATURES

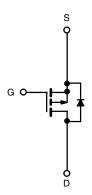
- TrenchFET® Power MOSFETs
- 175 °C Rated Maximum Junction Temperature





Ordering Information: SUU10P06-280L

SUU10P06-280L-E3 (Lead (Pb)-free)



P-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C		- 10		
Continuous Diam Current (1 _J = 150 °C)	T _C = 100 °C	l 'D	- 7		
Pulsed Drain Current		I _{DM}	- 20	А	
Continuous Source Current (Diode Conduction)		I _S	- 10]	
Avalanche Current		I _{AS}	- 10		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	5	mJ	
Maximum Davier Dissination	T _C = 25 °C	Pn	37	14/	
Maximum Power Dissipation	T _A = 25 °C		2 ^a	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Junction-to-Ambient ^a	FR4 Board Mount	R_{thJA}	60	70		
Junction-to-Ambient*	Free Air	' 'thJA	120	140	°C/W	
Junction-to-Case		R _{thJC}	3.7	4.0]	

Notes:

For SPICE model information via the Worldwide Web: http://www.vishay.com/www/product/spice.htm.

a. Surface Mounted on FR4 board.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

SUU10P06-280L

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SPECIFICATIONS $T_J = 25$ °	C, unless o	therwise noted					
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static	•				•		
Drain-Source Breakdown Voltage	V_{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0	- 2.0	- 3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$	-		- 1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50	μΑ	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 175 °C			- 150		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 10			Α	
		V _{GS} = - 10 V, I _D = - 5 A		0.130	0.170	Ω	
	Б	V _{GS} = - 10 V, I _D = - 5 A, T _J = 125 °C			0.31		
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 5 A, T _J = 175 °C			0.375		
		V _{GS} = - 4.5 V, I _D = - 2 A		0.210	0.280		
Forward Transconductance ^b	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A		6		S	
Dynamic							
Input Capacitance	C _{iss}			635		pF	
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		100			
Reverse Transfer Capacitance	C _{rss}			30			
Total Gate Charge	Q_g			11.5	25	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		3.5			
Gate-Drain Charge	Q_{gd}			2			
Turn-On Delay Time ^c	t _{d(on)}			9	20	ns	
Rise Time ^c	t _r	$V_{DD} = -30 \text{ V, } R_L = 3 \Omega$ $I_D \cong 10 \text{ A, } V_{GEN} = -10 \text{ V, } R_G = 2.5 \Omega$		16	20		
Turn-Off Delay Time ^c	t _{d(off)}			17	30		
Fall Time ^c	t _f			19	35		
Source-Drain Diode Ratings and Cha	racteristics	$T_C = 25 {}^{\circ}C^a$					
Pulsed Current	I _{SM}				- 20	Α	
Forward Voltage ^b	V_{SD}	$I_F = 10 \text{ A}, V_{GS} = 0 \text{ V}$			- 1.3	٧	
Reverse Recovery Time	t _{rr}	$I_F = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		50	80	ns	

Notes:

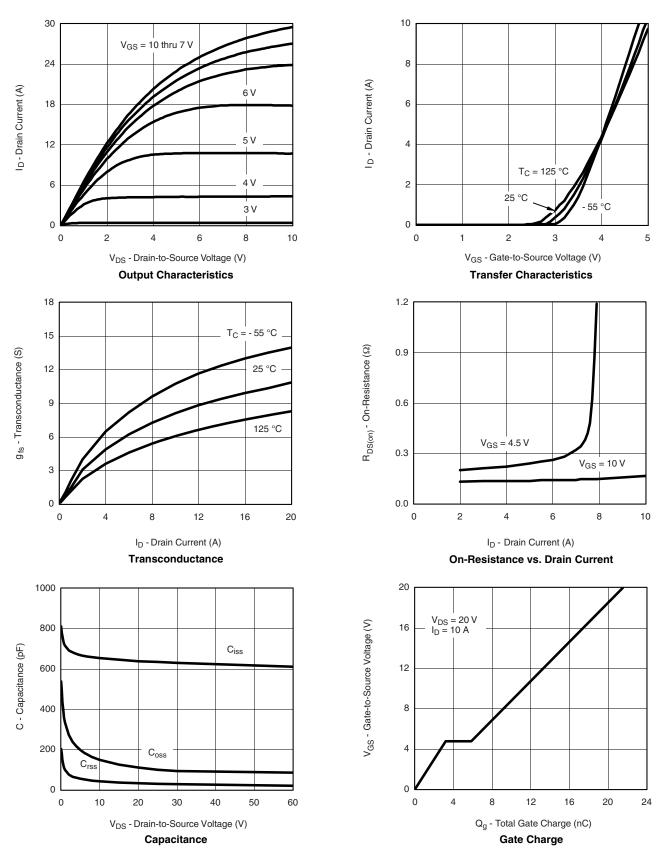
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





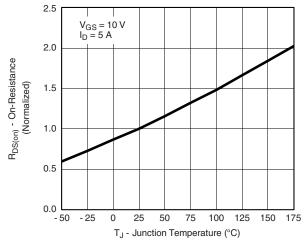
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



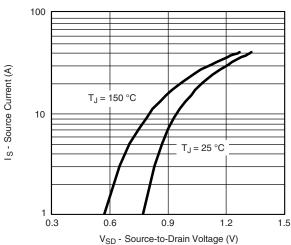
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

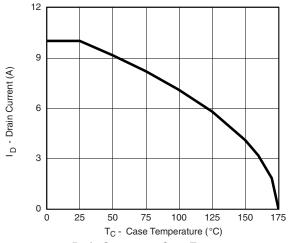


On-Resistance vs. Junction Temperature

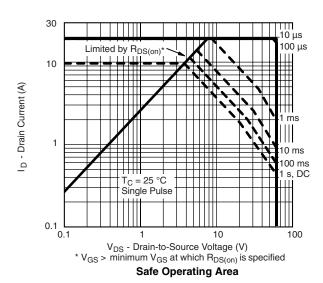


Source-Drain Diode Forward Voltage

THERMAL RATINGS



Drain Current vs. Case Temperature





Normalized Thermal Transient Impedance, Junction-to-Case

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Revision: 18-Jul-08

Document Number: 91000 www.vishay.com